

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1510-01	DATE: 6-Nov-2015	MEANS OF DISTINGUISHING CHANGED DEVICES:				
Product Affected: PDIP-28, 48 (Green p Refer to Attachment II for the aff		 Product Mark Back Mark Date Code Other Lot # will have: "GR" prefix for Greatek Electronics, Taiwan 				
Date Effective: 6-Feb-2016						
Contact: IDT PCN DESK		Attachment: Yes No				
E-mail: pcndesk@idt.com		Samples: Please contact your local sales representative for sample request.				
DESCRIPTION AND PURPOSE OF CH	ANGE:					
 Die Technology Wafer Fabrication Process Assembly Process Equipment This notification is to advise our customers that IDT is adding Greatek Electronics, Taiwan (GEI) as the alternate Assembly facility. 						
□ Material	There is no change to the moisture performance.					
 Testing Manufacturing Site Data Sheet Other 	Attachment I details the qualification data for this change and Attachment II shows the affected list of part numbers.					
RELIABILITY/QUALIFICATION SUM Refer to qualification data shown in Attach						
CUSTOMER ACKNOWLEDGMENT C	F RECEIPT:					
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.						
Customer:	□	Approval for shipments prior to effective date.				
Name/Date:	E-	Mail Address:				
Title:	Pł	one# /Fax# :				
CUSTOMER COMMENTS:						
IDT ACKNOWLEDGMENT OF RECE	<u></u>					
RECD. BY:		DATE:				



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

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ATTACHMENT I - PCN # : A1510-01

PCN Type:	Manufacturing Site - Alternate Assembly Location
Data Sheet Change:	None
	No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding Greatek Electronics, Taiwan (GEI) as the alternate Assembly facility.

The material set details of the current and alternate assembly location is as shown in Table 1. The die attach and mold compound used at the alternate assembly are qualified IDT materials. There is no change from the existing qualified lead frame material, lead finish, and wire for the alternate assembly location.

There is no change to the moisture performance.

	Existing Assembly (Amkor, Philippines)	Alternate Assembly (Greatek, Taiwan)	
Die Attach	8390A	CRM1076DJ-G	
Wire	Au wire	Au wire	
Mold Compound	CK5000A	G631M	



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Qualification Information and Qualification Data:

- Affected Packages: PDIP-28 & 48
- Assembly Material: The affected package type is using Greatek standard materials shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: PDIP-48

			Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3	
* HAST - Biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	25/0	25/0	25/0	
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0	
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0	

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test



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Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
7130LA35PDG	7204L15PDGI	7130LA55PDGI	7134LA25PDG
7201LA50PDG	7205L12PDG	7132LA35PDG	7134LA25PDGI
7202LA12PDG	7206L15PDG	7132LA35PDGI	7207L15PDG
7202LA15PDGI	7201LA35PDG	7132LA55PDGI	
7203L12PDG	7201LA12PDG	7132SA55PDG	
7204L12PDG	7140LA35PDG	7134LA20PDG	